

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	931	@ad<="20040330" and ('wiring board' or 'wiring tape') and 'solder ball' and ('printed circuit board' or 'PCB')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 10:15
L2	6	@ad<="20040330" and ('wiring board' or 'wiring tape') and 'solder ball' and ('printed circuit board' or 'PCB') and 'metal stud'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 10:15
L3	10	@ad<="20040330" and ('wiring board' or 'wiring tape') and 'solder ball' and ('printed circuit board' or 'PCB') and 'metal' with 'stud'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 10:16
L4	8	@ad<="20040330" and ('wiring board' or 'wiring tape') and 'solder ball' and ('printed circuit board' or 'PCB') and 'metal' with 'plug'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 10:16
L5	180	@ad<="20040330" and ('wiring board' or 'wiring tape') and 'solder ball' and ('printed circuit board' or 'PCB') and 'metal' with 'bump'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:15
L6	2	("6329610").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/20 10:56
L7	9	(("5811982") or ("5914614") or ("6329827") or ("6722032")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/20 11:08
L8	1	"5177438".PN.	USPAT; USOCR	OR	ON	2005/10/20 10:58
L9	1	"5576630".PN.	USPAT; USOCR	OR	ON	2005/10/20 10:58
L10	4	(("6288905") or ("6376769")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/20 11:08
L11	951	@ad<="20040330" and 'flexible' with 'substrate' and 'copper' and 'solder ball' and ('printed circuit board' or 'PCB')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:16

L12	353	@ad<="20040330" and 'flexible' with 'substrate' and 'copper' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:16
L13	51	@ad<="20040330" and 'wiring substrate' and 'copper' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:25
L14	233	@ad<="20040330" and 'wiring board' and 'copper' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:17
L15	4	@ad<="20040330" and 'wiring tape' and 'copper' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:17
L16	0	@ad<="20040330" and 'flexibel' same 'substrate' and 'copper' with 'pillar' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:25
L17	0	@ad<="20040330" and 'flexibel' same 'substrate' and 'copper' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:25
L18	0	@ad<="20040330" and 'flexible' same 'substrate' and 'copper' with 'pillar' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:26
L19	425	@ad<="20040330" and 'flexible' same 'substrate' and 'copper' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:28
L20	6	@ad<="20040330" and 'flexible' same 'substrate' and 'copper' same 'pillar' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:26
L21	105	@ad<="20040330" and 'flexible' same 'substrate' and 'copper' same 'bump' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:57
L22	5	@ad<="20040330" and 'flexible' same 'substrate' and 'copper' with 'stud' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:28
L24	1	"6010769".PN.	USPAT; USOCR	OR	ON	2005/10/20 11:36

L25	1	"5876842".PN.	USPAT; USOCR	OR	ON	2005/10/20 11:39
L26	1	"5744758".PN.	USPAT; USOCR	OR	ON	2005/10/20 11:39
L27	1	"5600103".PN.	USPAT; USOCR	OR	ON	2005/10/20 11:40
L28	1	"5510216".PN.	USPAT; USOCR	OR	ON	2005/10/20 11:40
L29	67	@ad<="20040330" and 'tape' same 'interposer' and 'copper' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 12:12
L30	2	("6081026").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/20 12:06
L31	1	"5854534".PN.	USPAT; USOCR	OR	ON	2005/10/20 12:09
L32	96	@ad<="20040330" and 'flexible' same 'interposer' and 'copper' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 12:12
L33	80	@ad<="20040330" and 'flexible' with 'interposer' and 'copper' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 12:12
S1	2	"20040201096"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 09:03
S2	2289	@ad<="20040330" and (257/678).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 09:13
S3	2099	@ad<="20040330" and (257/697-698).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 09:04
S4	1585	@ad<="20040330" and (257/700).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 09:04
S5	1913	@ad<="20040330" and (257/784).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 09:38

S6	1756	@ad<="20040330" and (257/786).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 09:07
S7	10	@ad<="20040330" and 'flexible' same 'wiring circuit' and 'solder ball' and 'printed circuit board'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 09:16
S8	1	"6580031".PN.	USPAT; USOCR	OR	ON	2005/10/20 09:10
S9	1	"6580031".PN.	USPAT; USOCR	OR	ON	2005/10/20 09:11
S10	6144	@ad<="20040330" and (361/749-750).ccls. or (361/760).ccls. or (361/792).ccls. or (361/795).ccls. or (257/686).ccls. or (257/685).ccls. or (257/688).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 09:16
S11	21	@ad<="20040330" and 'flexible' same 'wiring substrate' and 'solder ball' and 'printed circuit board'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 09:20
S12	864	S10 and 'flexible' with 'substrate'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 09:17
S13	235	@ad<="20040330" and 'wiring substrate' and 'solder ball' and 'printed circuit board'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 10:12
S14	1	"6285081".PN.	USPAT; USOCR	OR	ON	2005/10/20 09:30
S15	1	"6181569".PN.	USPAT; USOCR	OR	ON	2005/10/20 09:30
S16	1	"6114187".PN.	USPAT; USOCR	OR	ON	2005/10/20 09:31
S17	1	"6005292".PN.	USPAT; USOCR	OR	ON	2005/10/20 09:31
S18	1	"5900738".PN.	USPAT; USOCR	OR	ON	2005/10/20 09:33
S19	1	"5414371".PN.	USPAT; USOCR	OR	ON	2005/10/20 09:33
S20	1	"5086337".PN.	USPAT; USOCR	OR	ON	2005/10/20 09:33
S21	3938	@ad<="20040330" and (257/773-774).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 09:38